



THE COMPUTER ENGINEERING RESEARCH CENTER

THE VLSI SEMINAR SERIES

Dr. Yuan Xie

Pennsylvania State University

Challenges and Potentials in 3-D IC Designs

Abstract:

As fabrication of 3D integrated circuits is becoming viable, developing CAD tools and circuit/architectural techniques are imperative to explore the design space for 3D IC design. In this talk, I will give a brief introduction on the research activities in my group at Penn State University, including 3D EDA tool development that helps the adoption of 3D ICs, micro-architecture design to explore the potentials of using 3D technology (especially for multi-core designs), and system-level cost analysis for 3D ICs (more details can be found at our 3D research page: <http://www.cse.psu.edu/~yuanxie/3d.html>)

Biography:

Yuan Xie is Associate Professor in Computer Science and Engineering department at the Pennsylvania State University. He received the B.S. degree from Tsinghua University, and Ph.D. degrees from Princeton University. Before joining Penn State in Fall 2003, he was with IBM Microelectronic Division. He was a recipient of the NSF CAREER award in 2006, and IBM Faculty Award in 2008, Outstanding Teaching Award in 2008. He received Best Paper Award in ASP-DAC 2008, and Best Paper Award Nomination in ICCAD 2006, ASP-DAC 2009. He is Associate Editor for IEEE Transaction on VLSI, and has served as a TPC member in many conferences. His research interests include VLSI Design, computer architecture, embedded systems design, and EDA.

Thursday, Sept. 25, 2008, CPE 2.220, 4:00 PM- 5:30PM

<http://www.cerc.utexas.edu/vlsi-seminar/>